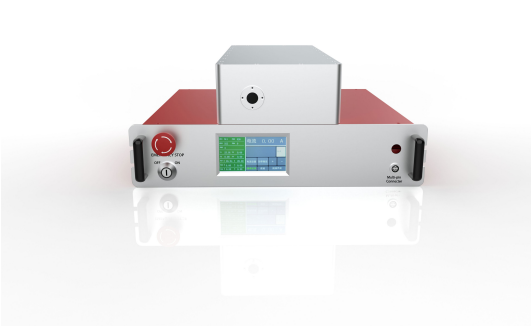
1099nm Nanosecond laser

ULTRAFAST PULSED LASERS



1099nm Nanosecond laser Laser Stealth Dicing is a non-contact cutting technique that can cut semiconductor materials accurately and efficiently. The wafer Stealth Dicing laser introduced by Precilasers has achieved high quality stealth dicing on a variety of wafer materials. The infrared laser's pulse width and waveform can be adjusted, also feature with pulse width and repetition rate be adjusted continuouly, to achieve accurate processing of the wafer.

- High Power Waveform Can
- Be Edited Good Beam
- Quality Pulse Width Adjustable
- Repetion Rate Asjustable

Specifications

Parameter	FL-NSF-1099-20-QCW
Center Wavelength	1099nm
Pulse Width	100-800ns (adjustable)
Repetition Rate	50-200kHz (adjustable)
Average Power	15W / 20W / 30W
Beam Diameter	3±0.2mm
Beam Divergence (full angle)	<0.5mrad
Beam Circularity	>95%
Beam Quality	TEM00, M^2<1.2
Polarization	linear,>20dB
Power Stability	<0.3% @3hours, RMS
Waveform	Gaussian/Square waveform
Cooling	Water cooling
Cold Start	<2 hours
Warm Start	<15 minutes
Controller Size	≤483mm x 422mm x 105mm
Laser Head Size	≤68.5mm x 278mm x 46mm / ≤520mm x 200mm x 95mm
Chiller Size	≤58cm x 29cm x 52cm
Laser Head Weight	≤10kg / ≤15kg
Laser Controller Weight	≤20kg
Chiller Weight	≤25kg
Cable Length Between Laser Head And Controller	fiber length>2m
Operating Temperature (No condensing)	15-35 °C (water cooling)
Power Supply	100V-240V, AC, 50/60Hz
Power Consumption	<200W / <250W
Communication	RS422

Source: WaveQuanta product database. For ordering, customization (wavelength, power, package) and quotation, contact sales@wavequanta.com.